100% Material Declaration Data Sheet FFG665

Average Weight: 5.6330 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.322090**	**5.718%**
	Silicon	7440-21-3	100.00		0.322090	
Solder Bump					**0.018510**	**0.329%**
	Tin	7440-31-5	63.00		0.011661	
	Lead	7439-92-1	37.00		0.006849	
Underfill					**0.056000**	**0.994%**
	Silica	60676-86-0	70.00		0.039200	
	Epoxy Resin A	9003-36-5	20.00		0.011200	
	Epoxy Resin B	25068-38-6	3.00		0.001680	
	Hardener	19900-65-3	7.00		0.003920	
Heat Spreader					**2.800000**	**49.707%**
	Copper	7440-50-8	99.60		2.788800	
	Nickel	7440-02-0	0.40		0.011200	
Heat Spreader Adhesive					**0.062000**	**1.101%**
	Organopolysiloxane mixture	N/A	100.00		0.062000	
Substrate					**1.818880**	**32.290%**
	Cu	7440-50-8	46.91	metal layer	0.853237	
	Ni	7440-02-0	0.52	metal layer	0.009458	
	Au	7440-57-5	0.12	metal layer	0.002183	
	Glass fiber	NA	10.50		0.190982	
	Halogen fire retardant	NA	5.25		0.095491	
	BT (core)	NA	28.00		0.509286	
	Solder mask	NA	8.70		0.158243	
Solder Balls					**0.555520**	**9.862%**
	Tin	7440-31-5	95.50		0.530522	
	Silver	7440-22-4	4.00		0.022221	
	Copper	7440-50-8	0.50		0.002778	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
4/9/07	1.0	Initial release.

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